

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Xiang Dai et al.	Examiner:	James M. Mitchell
Serial No.:	10/612,663	Group Art Unit:	2813
Filed:	July 2, 2003	Docket No.:	200308566-1
Title:	SUPPORTING A CIRCUIT PACKAGE INCLUDING A SUBSTRATE HAVING A SOLDER COLUMN ARRAY		

OK TO ENTER: /J.m.m/ **AMENDMENT AFTER ALLOWANCE UNDER 37 C.F.R. § 1.312**

02/26/2008

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

This Amendment after Allowance under 37 C.F.R. § 1.312 is responsive to the Notice of Allowance mailed November 22, 2007. Please amend the above-identified patent application as follows: